

Title (en)

Method, device and adhesive tape for splicing label tapes and spliceable label tape

Title (de)

Verfahren, Vorrichtung und Klebeband zum Spleißen von Etikettenbändern sowie spleißbares Etikettenband

Title (fr)

Procédé, dispositif et bande adhésive pour l'épissage de bandes d'étiquettes et bande d'étiquettes pouvant être épissées

Publication

EP 2295355 B1 20140618 (DE)

Application

EP 10171750 A 20100803

Priority

DE 102009041017 A 20090910

Abstract (en)

[origin: EP2295355A2] The method involves holding a subsequent label strip (3) in a supplying position (B), and combining the subsequent label strip and a front label strip (2) for producing a spliced connection. The subsequent label strip is held by influencing a magnetic field. The magnetic field is produced by a permanent magnet (7). Independent claims are also included for the following: (1) a device for splicing label strips; (2) a label strip comprises a magnetic end section; and (3) an adhesive tape for splicing label strips.

IPC 8 full level

B65H 19/18 (2006.01)

CPC (source: EP)

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Citation (examination)

EP 0446901 A2 19910918 - HITACHI LTD [JP]

Cited by

IT202100012035A1; US2022080692A1; US11780202B2; WO2015185887A1; US10589952B2; EP3022142B1

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DOCDB simple family (publication)

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